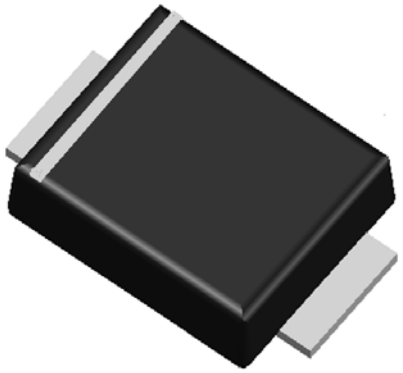
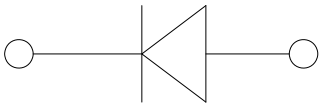
Surface Mount General Purpose Rectifier





Features

- Low profile package
- Ideal for automated placement
- Glass passivated chip junction
- High forward surge capability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

Typical Applications

For use in general purpose rectification of power supplies, inverters, converters, and freewheeling diodes for consumer and telecommunication.

Mechanical Data

- **Package**: SMBF
  Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant, halogen-free
- **Terminals**: Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** Cathode line denotes the cathode end

■Maximum Ratings (T_a=25℃ Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	GS2ABF	GS2BBF	GS2DBF	GS2GBF	GS2JBF	GS2KBF	GS2MBF
Device marking code			GS2ABF	GS2BBF	GS2DBF	GS2GBF	GS2JBF	GS2KBF	GS2MBF
Maximum Repetitive peak reverse voltage	V_{RRM}	V	50	100	200	400	600	800	1000
Maximum RMS Voltage	V_{RMS}	V	35	70	140	280	420	560	700
Maximum DC Blocking Voltage	V_{DC}	V	50	100	200	400	600	800	1000
Average rectified output current @60Hz sine wave, resistance load, TL (Fig.1)	IO	A	2.0						
Forward Surge Current (Non-repetitive) @60Hz Half-sine wave,1 cycle, Tj=25℃	I_{FSM}	A	50						
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, Tj=25℃			100						
Current squared time @1ms≤t≤8.3ms Tj=25℃	I^2t	A^2s	10.375						
Storage temperature	Tstg	℃	-55 ~ +150						
Junction temperature	Tj	℃	-55 ~ +150						

■Electrical Characteristics（T_a=25℃ Unless otherwise specified）

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	GS2ABF	GS2BBF	GS2DBF	GS2GBF	GS2JBF	GS2KBF	GS2MBF
Maximum instantaneous forward voltage	VF	V	IFM=2.0A	1.1						
Maximum DC reverse current at rated DC blocking voltage	IR	μA	T_j =25℃	5.0						
			T_j =125℃	100						
Typical junction capacitance	Cj	pF	Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C	12						

■Thermal Characteristics （T_a=25℃ Unless otherwise specified）

PARAMETER	SYMBOL	UNIT	GS2ABF	GS2BBF	GS2DBF	GS2GBF	GS2JBF	GS2KBF	GS2MBF
Typical Thermal Resistance	$R_{\theta J-A}$(1)	℃/W	60						
	$R_{\theta J-L}$(1)		20						
	$R_{\theta J-C}$(1)		15						

Note:
(1) Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.3" x 0.3" (8.0 mm x 8.0 mm) copper pad areas

■ Characteristics (Typical)

FIG.1: Io-TL Curve

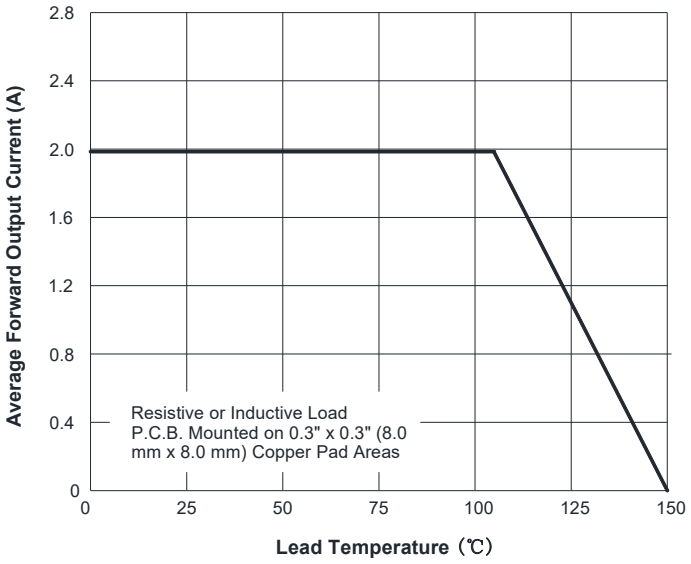


FIG.2: Forward Surge Current Capability

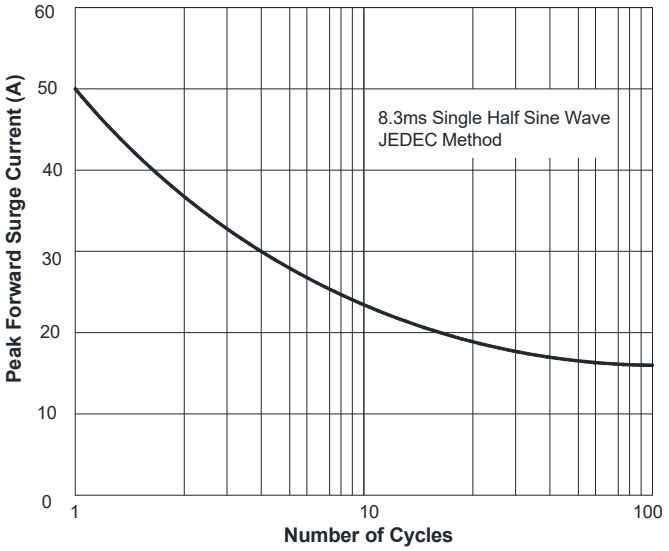


FIG.3: Typical Forward Voltage

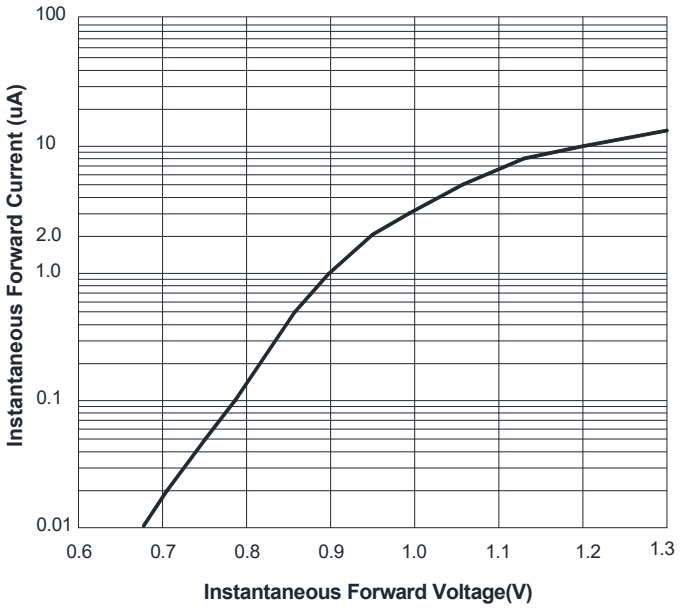
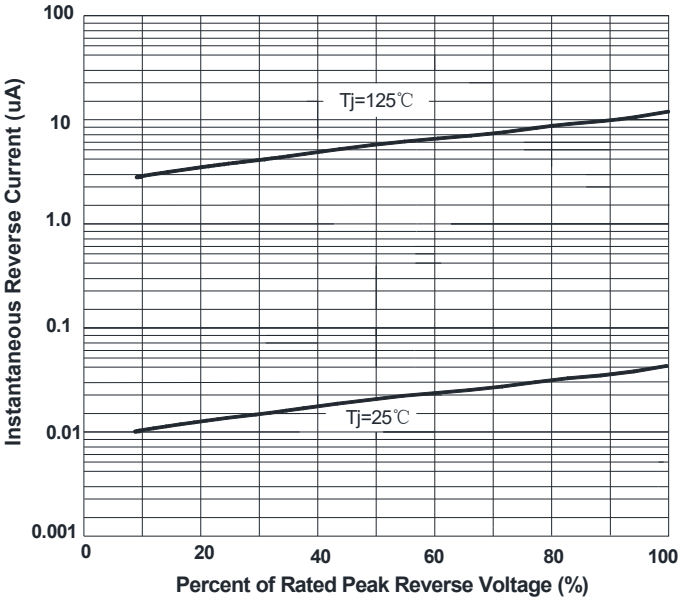


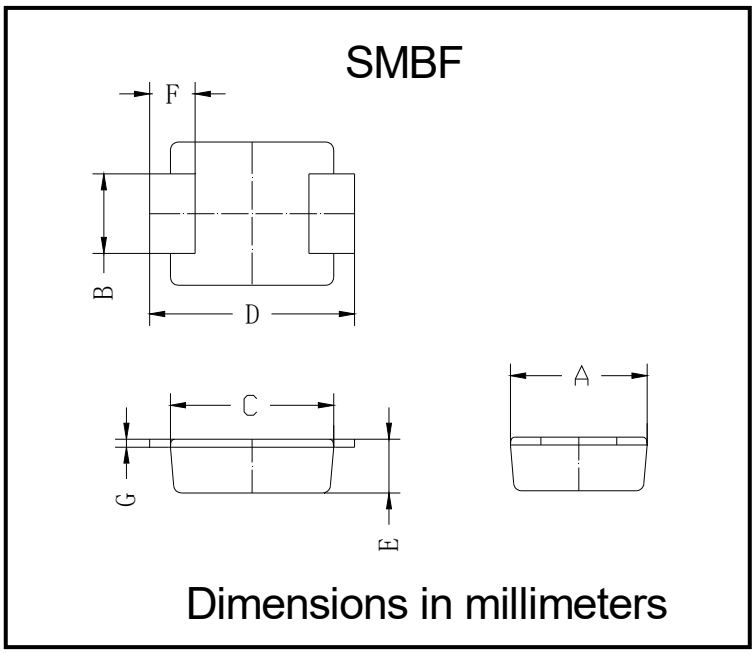
FIG.4: Typical Reverse Characteristics



■Ordering Information (Example)

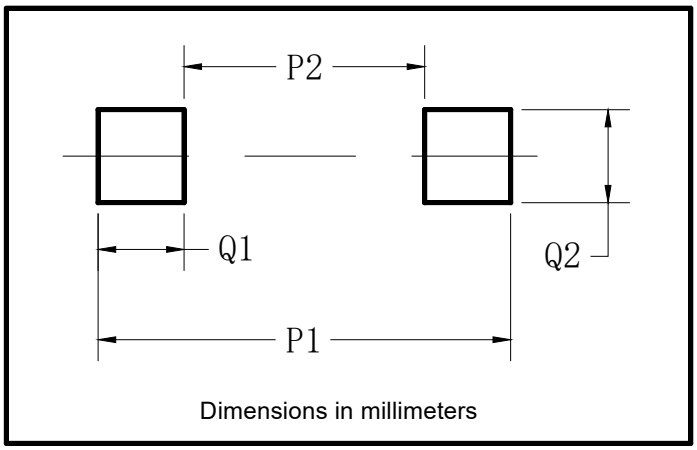
PREFERED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
GS2ABF - GS2MBF	F1	Approximate 0.065	5000	/	80000	13” reel

■ Outline Dimensions



SMBF		
Dim	Min	Max
A	3.40	3.80
B	1.90	2.10
C	4.15	4.45
D	5.10	5.60
E	1.05	1.55
F	0.70	1.35
G	0.15	0.25

■ Suggested pad layout



Dim	Milimeters
P1	6.20
P2	2.40
Q1	1.90
Q2	2.20

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